



DATA SHEET

CHIP Low Impedance 105°C

Serie: I15008

Voltage: 25Volt

Range: 22μF

Impedance: 1,8Ω

Dimension 5x5,4mm

Ripple Current: 95mA

CHIP Low Impedance 105°C

Serie No.: I15008

Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 7	

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

Voltage:	25Volt
Range;	22μF
Dimension; D x L mm	5x5,4mm
Impedance (Ω) max., at 20°C, 100kHz	1,8Ω
Ripple Current (mA rms) at 105°C, 100kHz	95mA

Ordering Code			
250	Voltage		
220	Range		
D=	B	L=	0

Low Impedance with Operating Temperatur Range of -55°C ~ +105°C

Load Life of 1000~2000hours

Leakage current max.	Ø4 ~ Ø10mm		I= 0,01CV or 3µA whichever is greater (after 2 minutes)											
	Ø12,5 ~ Ø16mm		I= 0,03CV or 4µA whichever is greater (after 1 minutes)											
Capacitance tolerance	± 20% at 120Hz, 20°C													
Dissipation factor max. (at 120Hz, 20°C)	WV		6,3	10	16	25	35	50						
	Tanδ	Ø4 ~ Ø10mm	0,22	0,19	0,16	0,14	0,12	0,12						
		Ø12,5 ~ Ø16mm	0,26	0,22	0,18	0,16	0,14	0,12						

Low Temperatur characteristics (Impedance ratio at 120Hz)	WV		6,3	10	16	25	35	50						
	Ø4 ~ Ø10mm	Z-25°C / Z+20°C	2	2	2	2	2	2						
		Z-55°C / Z+20°C	5	4	4	3	3	3						
	Ø12,5 ~ Ø16mm	Z-25°C / Z+20°C	3	3	2	2	2	2						
Z-55°C / Z+20°C		10	8	6	4	3	3							
Load Life (after aplication of the rated voltage for 2000hrs at 105°C	Leakagge current			Less than specified value									CHIP Low Impe	
	Capacitance Change			Within ±20% of initial value										
	Tanδ			Less than 200% of specified value										
	Ø4 ~ Ø6,3x5,4: 1000hours													

CHIP Low Impedance 105°C

Part No.: **I15008**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.		2 from 7	

www.edcon-components.com

email: info@edcon-components.com

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board
Emboss carrier tape packing systems is available for automatic insertion



Shell life (at 105°C)	After 1000hours no load test, leakage current, capacitance and tan δ are same as load life value.
-----------------------	--

Resistance to soldering heat	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within $\pm 10\%$ of initial value
	Tan δ	Less than specified value

Size	FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT						
	Capacitance	Frequency					
	μF	50Hz	120Hz	300Hz	1KHz	10KHz $\leq$	
$\varnothing 4 \sim \varnothing 10\text{mm}$	1,0~ 68	0,35	0,50	0,64	0,83	1,00	
	100~2200	0,40	0,55	0,70	0,85	1,00	
$\varnothing 12,5 \sim \varnothing 16\text{mm}$	~680	0,45	0,65	0,80	0,90	1,00	
	1000 ~4700	0,65	0,85	0,95	1,00	1,00	

CHIP Low Impedance 105°C	
Part No.:	I15008
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		3 from 7

EDCON-COMPONENTS



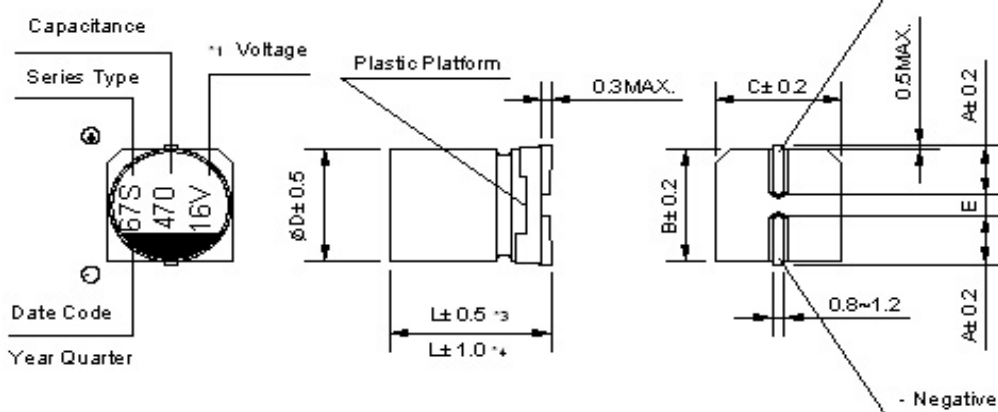
Designed for surface mounting on high density circuit board
Emboss carrier tape packing systems is available for automatic insertion



Technical Drawing

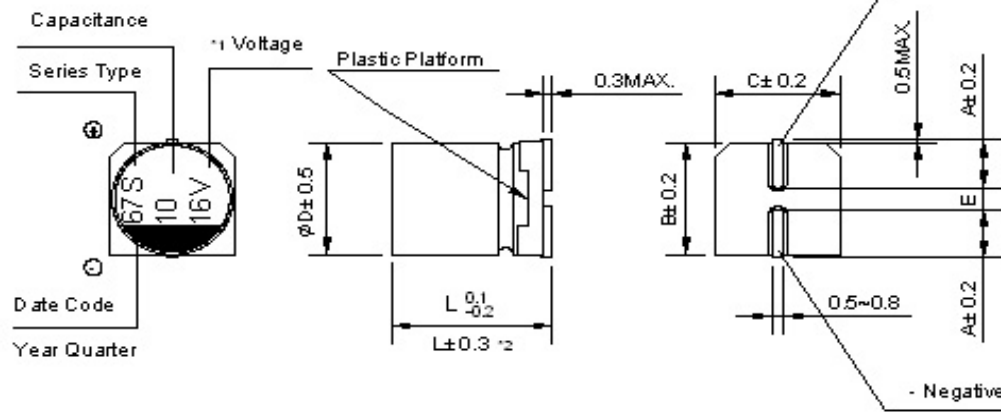
Dimension of Size Ø 8x10,5 ~ 16mm

(Ø 8x10,5~Ø 16)



Dimension of Size Ø 4~ 8x6,2mm

(Ø 4~Ø 8x6.2)



D x L	Ø 4 x 5,4	Ø 5 x 5,4	Ø 6,3 x 5,4	Ø 6,3 x 7,7	Ø 8 x 6,2	Ø 8 x 10,5	Ø 10 x 10,5	Ø 10 x 13,5	Ø 12,5 x 13,5	Ø 12,5 x 16	Ø 16 x 16,5
A	2,0	2,2	2,6	2,6	3,4	3,0	3,3	3,3	4,9	4,9	5,8
B	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
C	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
E +/-0.2	1,0	1,3	1,9	1,9	2,3	3,1	4,7	4,7	4,7	4,7	6,4
L	5,4	5,4	5,4	7,7	6,2	10,5	10,5	13,5	13,5	16,0	16,5

*1 Voltage mark (6V) represents 6,3V for Ø 4 ~ 10mm

*3 (L +/- 0.5) is applicable to Ø 8x10,5 ~ Ø 10mm

*2 (L +/- 0.3) is applicable to Ø 6,3 ~ 7.7 and Ø 8 + 6,2mm

*4 (L +/- 1.0) is applicable to Ø 12,5 ~ Ø 16mm

RE. Date code and series type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Series S

CHIP Low Impedance 105°C

Part No.: **I15008**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		4 from 7

Customer:

www.edcon-components.com

email: info@edcon-components.com

Copyright by S.Tiede

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board
Emboss carrier tape packing systems is available for automatic insertion

Emboss carrier tape packing systems is available for automatic insertion
--

[illegible]

Diameter ordering Code D	Code
3mm	3
4mm	A
5mm	B
6,3mm	C
8mm	E
10mm	G
12,5mm	I
16mm	K

Height ordering Code L	Code
4mm	A
5,4mm	0
5,8mm	1
6,2mm	2
7,7mm	3
10,5mm	4
13,5mm	5
16mm	6
16,5mm	7

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		5 from 7

CHIP Low Impedance 105°C	
Part No.:	I15008
Customer:	

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
-------	--------------	----------------	------------	-------------	-------------	------------------	------	--------------	--	--

I15008	250	M	220	B	0	XX	R	TR		
---------------	------------	----------	------------	----------	----------	-----------	----------	-----------	--	--

look table Voltage Code	M= ±20%	Ordering Code Range	Look table Code D	Look table Code L	XX= No function	R= ROHS Conform N= NON ROHS Conform	TR= Tape Reel Packing BU= Bulk- Ware		
----------------------------	----------------	------------------------	----------------------	----------------------	---------------------------	---	---	--	--

CHIP Low Impedance 105°C

Part No.: **I15008**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.		6 from 7

Customer:
email: info@edcon-components.com

www.edcon-components.com

EDCON-COMPONENTS

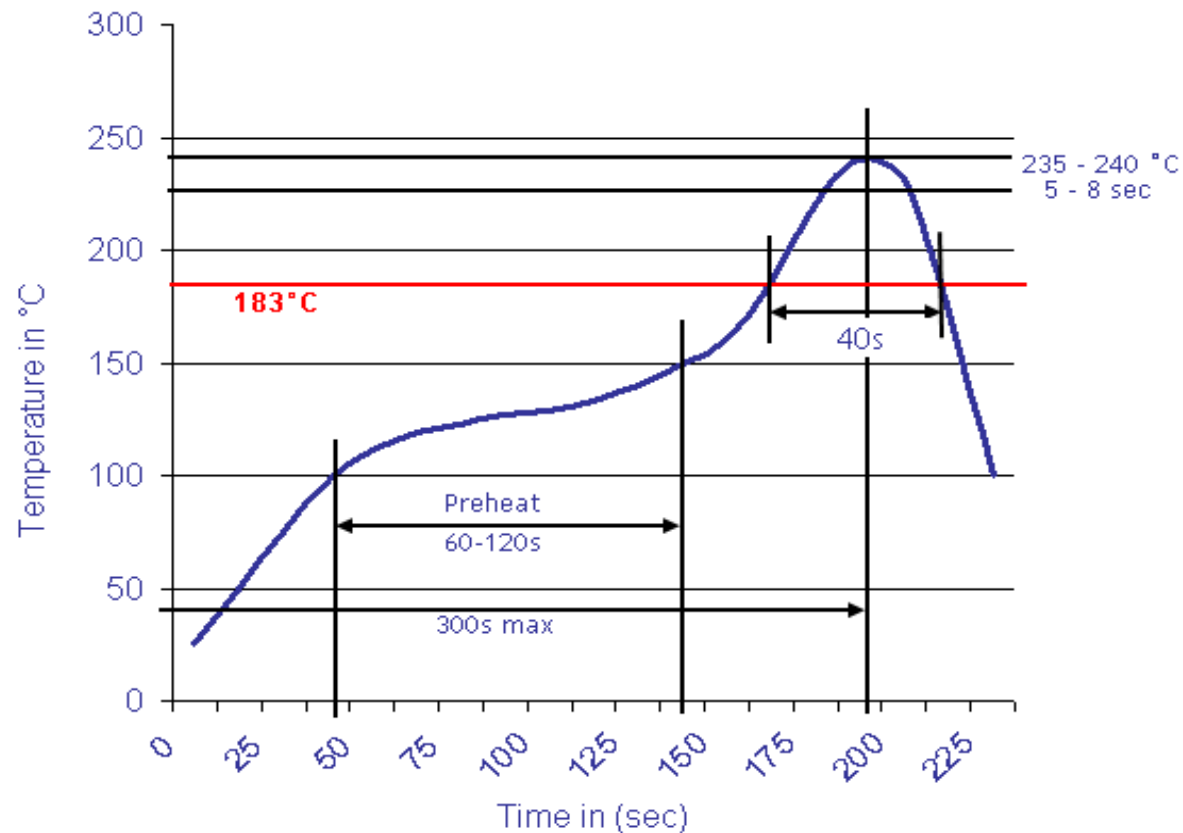


Designed for surface mounting on high density circuit board
Emboss carrier tape packing systems is available for automatic insertion



Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



CHIP Low Impedance 105°C

Part No.: **I15008**

DRW:	Jason	CHKD:	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	7 from 7		

www.edcon-components.com

email: info@edcon-components.com